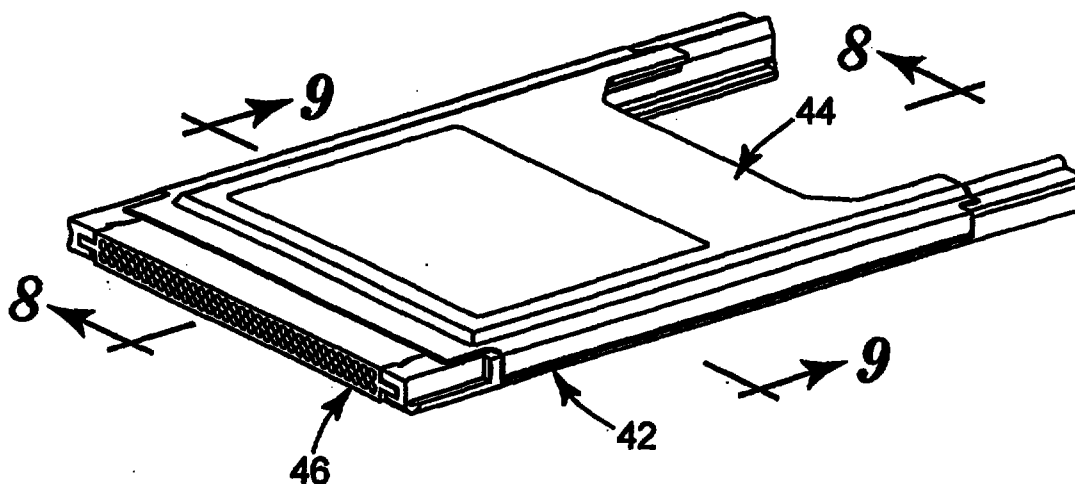




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<p>(21) International Application Number: PCT/US97/22122 (22) International Filing Date: 5 December 1997 (05.12.97) (30) Priority Data: 08/906,325 5 August 1997 (05.08.97) US (71) Applicant: MINNESOTA MINING AND MANUFACTURING COMPANY [US/US]; 3M Center, P.O. Box 33427, Saint Paul, MN 55133-3427 (US). (72) Inventors: FELDMAN, Steven; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). BASHKIN, Michael; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). (74) Agents: MCNUTT, Matthew, B. et al.; Minnesota Mining and Manufacturing Company, Office of Intellectual Property Counsel, P.O. Box 33427, Saint Paul, MN 55133-3427 (US).</p>		<p>(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, HU, ID, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i></p>

(54) Title: **PLASTIC CASED IC CARD ADAPTER ASSEMBLY**



(57) Abstract

An IC card adapter includes a printed circuit board attached on a first edge to solder tails extending from a first connector and on an opposing second edge to solder tails extending from a second connector. The printed circuit board, first connector and second connector form a subassembly. The subassembly is provided with a first keyed interlock surface which mates with a second keyed interlock surface on a lower molded housing adapted to receive the subassembly. The first and second keyed interlock surfaces orient the subassembly and lower housing. The lower molded housing also includes a first latching member which snap-fits with a second latching member on an upper molded housing. When the lower and upper housings are engaged, they define a cavity which encloses the printed circuit board.